

ABSTRACT

An integrated interconnect package for a semiconductor die and a method for assembling the die into the integrated interconnect package. The method may comprise placing the active face of the die onto an adhesive disposed on a sacrificial carrier, and applying an encapsulant over the backside of the die, forming a substantially rigid assembly structure. The assembly structure is separated from the adhesive, and an insulating material is applied to the active face of the die and patterned by a photolithography operation, creating at least one opening through the insulating material for exposing at least one die bond pad. A conductive material is then applied over the insulating material, flowing into the openings to contact the bond pads. The conductive material is then patterned by a photolithography operation, removing at least a portion of the conductive material to create a plurality of electrical traces and package terminals.